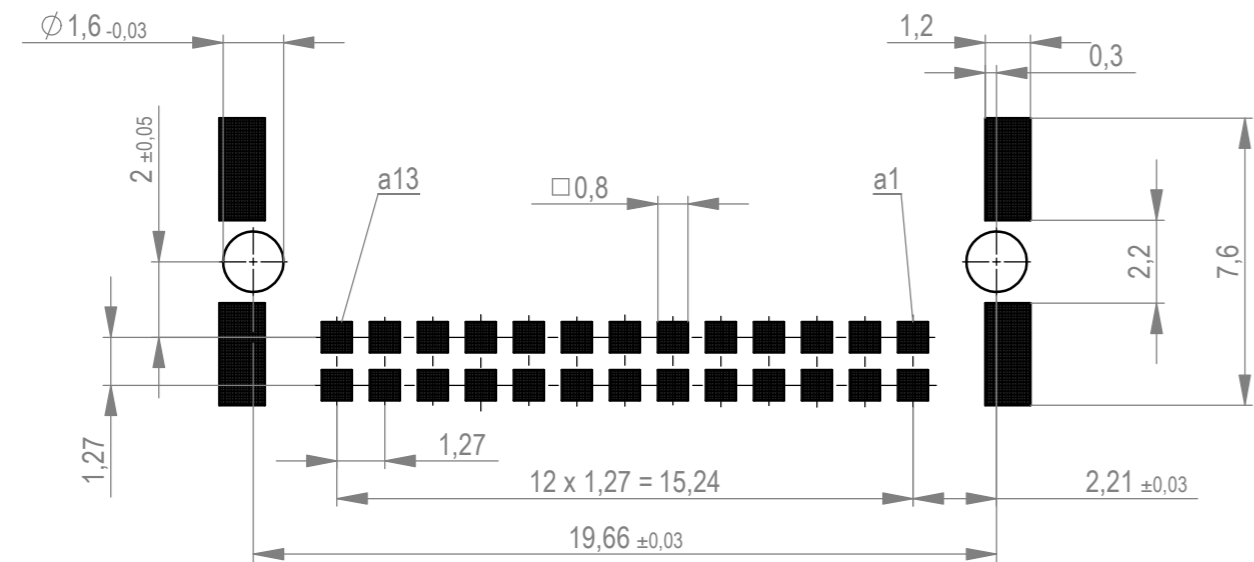
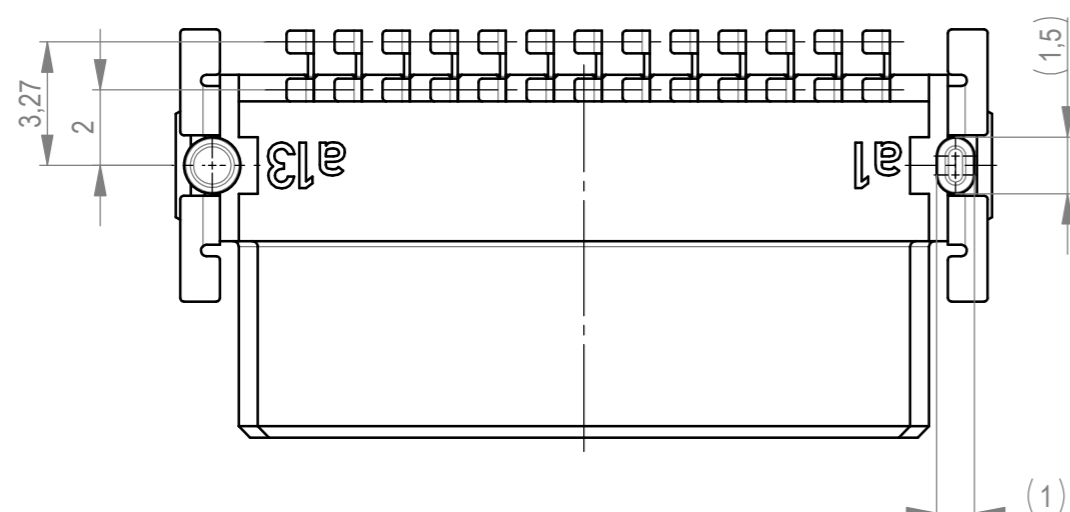
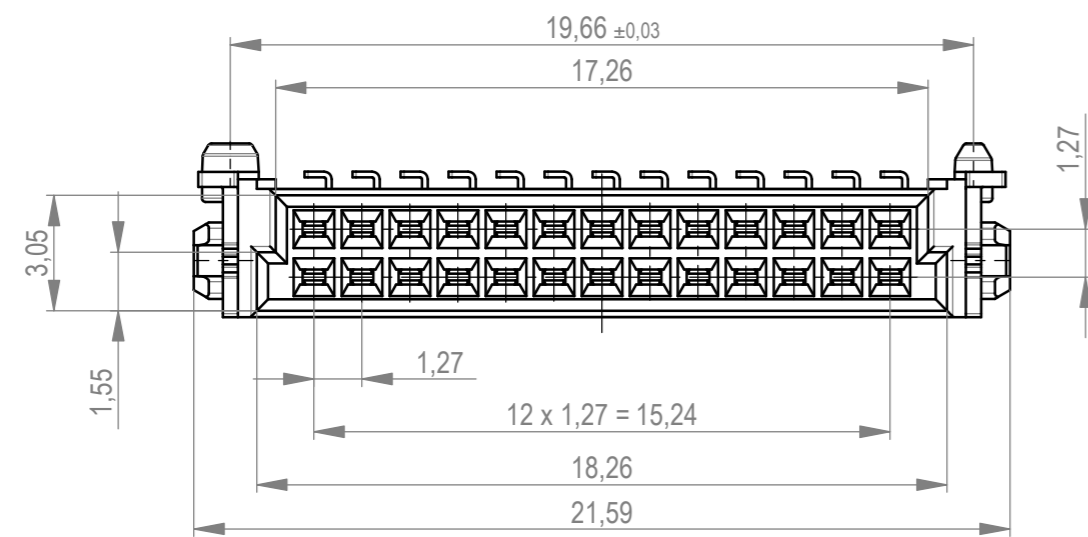
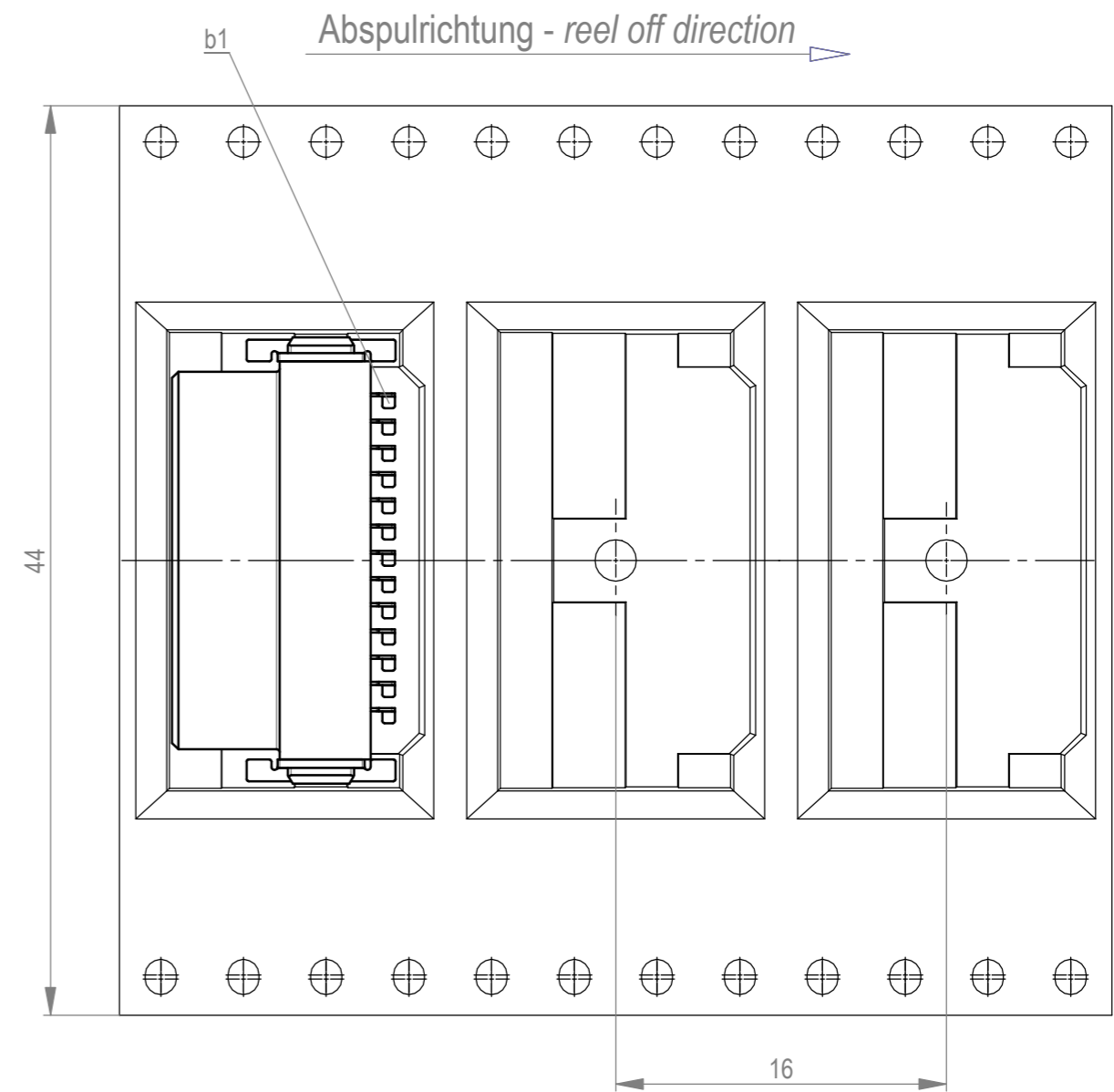
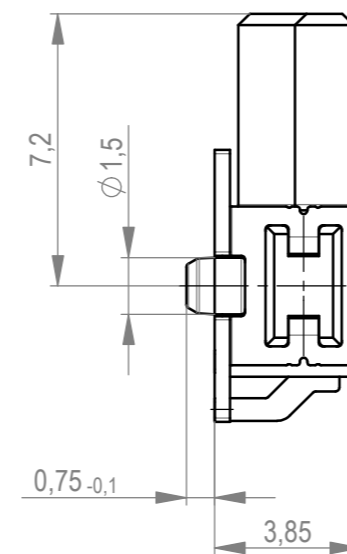
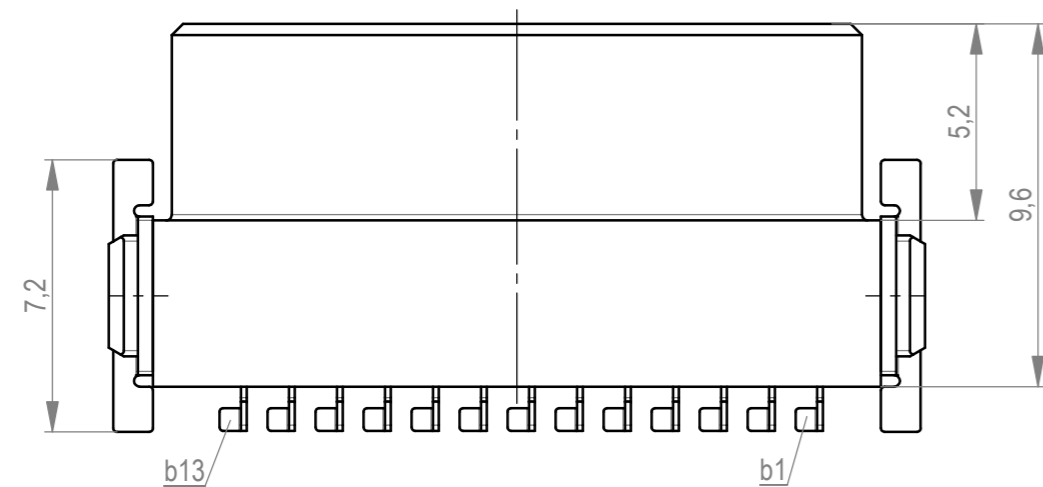
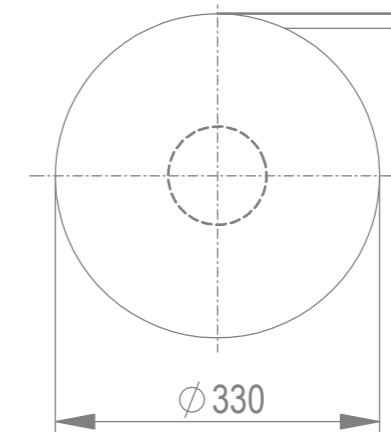


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



Verpackt im Gurt in Anlehnung an DIN IEC 60286-3  
tape on reel packaging according to DIN IEC 60286-3  
Verpackungseinheit: 560 Stück  
packaging unit: 560 pcs



Anforderungsstufe 1  
performance level 1

Kontaktbereich vergoldet  
mating area gold plating

Anschlussbereich verzinkt 4-6  $\mu\text{m}$   
terminal area 4-6  $\mu\text{m}$  tin plating

Koplanarität der Anschlüsse  $\leq 0,1 \text{ mm}$   
coplanarity area of termination  $\leq 0,1 \text{ mm}$

BA7-03 - Standard Bauhöhe  
type7-03 - standard assembly height

Wichtigste Version dieser Zeichnung dient zur Erreichung der  
Handlung. Bei Abweichungen vom englischen Original gilt das  
englische Original. In case of any deviation the English version shall prevail.  
The most important version of this drawing has been created for convenience only  
and may deviate from the original.  
In case of any deviation the English version shall prevail.

Dimension no.	Tolerances Dim. for Information ISO 8015		Scale Material 5:1
Customer drawing: This Drawing is a controlled Document.	Subject to modification without prior notice. Drawing will not be updated.		<b>ERNI-SMC</b> Female Connector Q SMT Type 7-03 26p <b>C-154741-E</b>
H1 Index	14.03.2025 Date		